



# 華泰電子股份有限公司

Orient Semiconductor Electronics ,Ltd.

( 股票代號 : 2329 )

2026年法人說明會

INVESTOR CONFERENCE

15 MAY ,2026

# 簡報大綱

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# 公司簡介



# 公司歷史



○ 資本額 Capital : US\$ 209M(NTD6.59B)  
Common Stock : US\$ 209M(NTD6.59B)

○ **2026**

55th Anniversary Celebration

○ **2015 & 2020**

Strategic Partnership Announcement

○ **2014**

1st 16D microSD in the world

○ **2005**

Biz Transformation into Memory Market

○ **Apr, 1994**

IPO in Taiwan Stock Exchange (TSE: 2329)

○ **1971 Established**

Founder : Dr. Eugene C. Y. Duh

Headquarters : Kaohsiung, Taiwan

# 公司生產據點



Headquarters (Flash Memory)  
(750,000 sq. ft.)

- » 6 Production buildings in NTIP
- » Headcount : around 5,700



Facility 2  
(59,223 sq. ft.)



LIC  
(256,200 sq. ft.)



Facility 3  
(158,638 sq. ft.)



Facility 1  
(146,475 sq. ft.)



Facility 5  
(190,000 sq. ft.)

# 公司組織

Chairman  
Tony Tung

President  
C. J. Tu

Testing Group

- Memory IC Testing Service
- Logic IC Testing Service

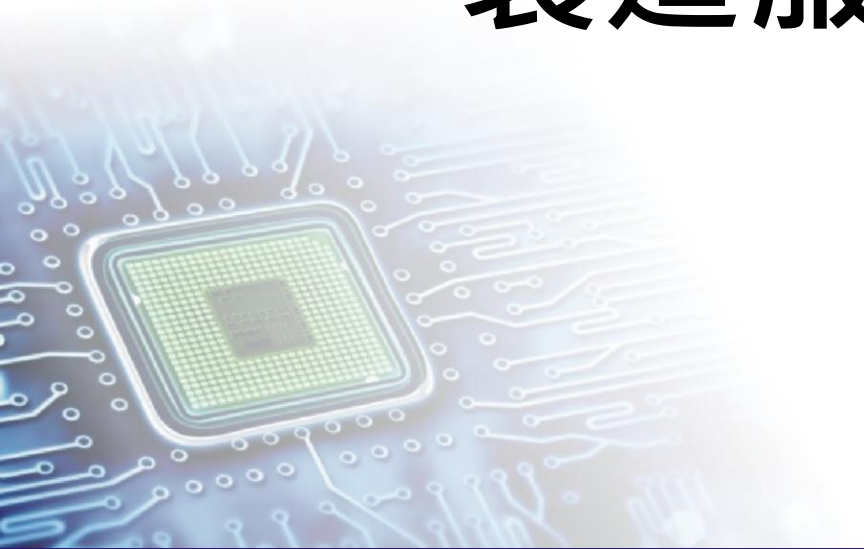
Semiconductor Group

- Memory IC Packaging Service
- Logic IC Packaging Service

EMS Group

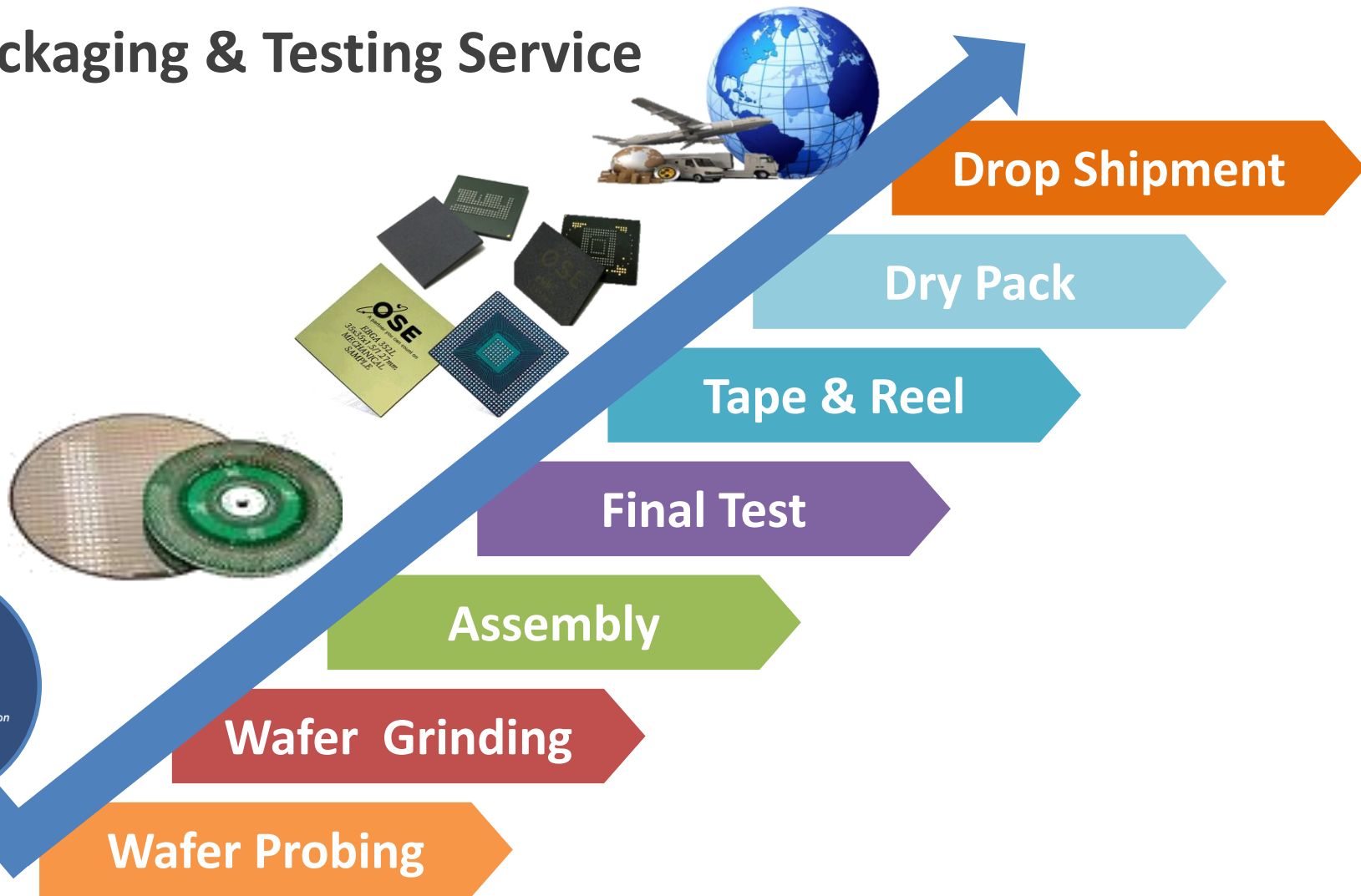
- EMS Service

# 製造服務及產品



# IC生產流程

» IC Packaging & Testing Service



# EMS生產流程

## Electronics Manufacturing Service



Product Design  
from Customer

JDM, DFM, DFT

NPI & Quick Turn  
Prototyping

Material  
Procurement

PCB Assembly

Repair and  
Upgrade

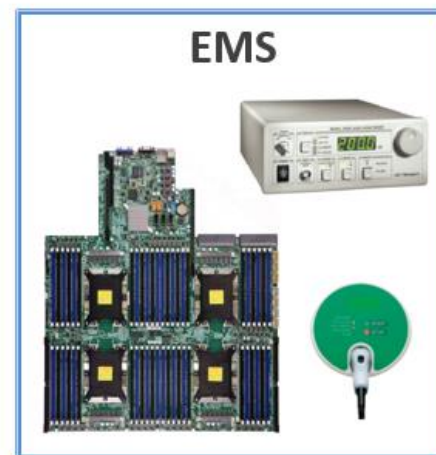
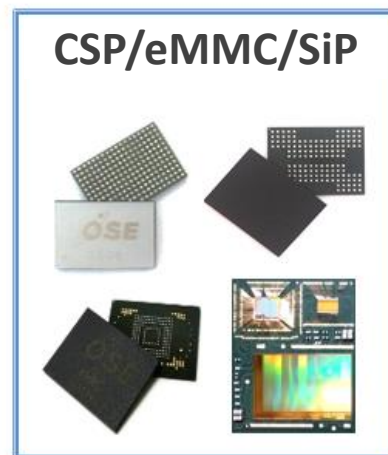
Distribution  
Support

System  
Integration

Box Build

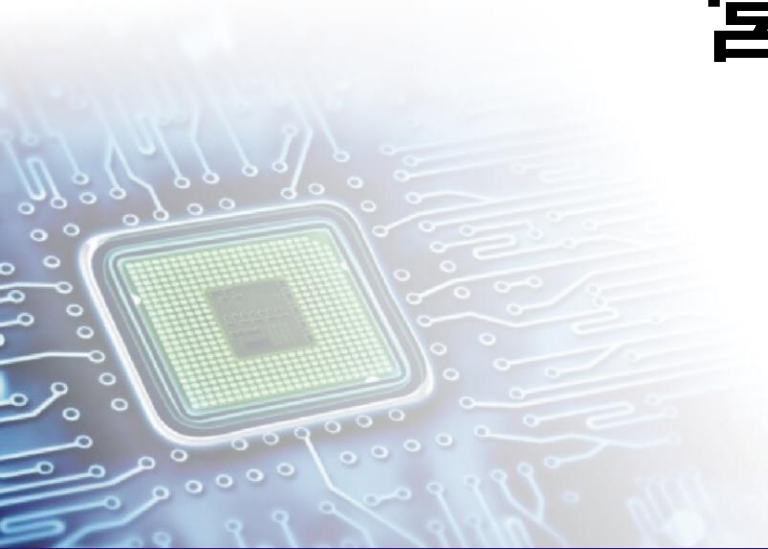
Functionality  
& Reliability  
Testing

# 產品及應用



\*Includes Wire Bond Type, Flip Chip Type, SiP, etc

# 2026 Q1 營運成果



# 合併綜合損益表(與上一季比較)

(單位：新台幣仟元)	Q1/2026	%	Q4/2025	%	季變化
營業收入淨額	4,860,476	100.00%	5,153,981	100.00%	(5.69%)
營業毛利	621,703	12.79%	791,370	15.35%	(21.44%)
營業淨利(淨損)	272,602	5.61%	422,215	8.19%	(35.44%)
稅前淨利(淨損)	291,646	6.00%	481,085	9.33%	(39.38%)
所得稅利益(費用)	(57,016)	(1.17%)	(77,182)	(1.50%)	(26.13%)
非控制權益	-	-	-	-	-
歸屬於本公司業主之淨利	234,630	4.83%	403,903	7.84%	(41.91%)
基本每股盈餘(新台幣元)	0.33	-	1.04	-	-
EBITDA	592,442	12.19%	762,747	14.80%	(22.33%)

# 合併綜合損益表(與去年同期比較)

(單位：新台幣仟元)	Q1/2026	%	Q1/2025	%	年變化
營業收入淨額	4,860,476	100.00%	4,077,476	100.00%	19.20%
營業毛利	621,703	12.79%	538,557	13.21%	15.44%
營業淨利(淨損)	272,602	5.61%	196,762	4.83%	38.54%
稅前淨利(淨損)	291,646	6.00%	231,357	5.67%	26.06%
所得稅利益(費用)	(57,016)	(1.17%)	(44,078)	(1.08%)	29.35%
非控制權益	-	-	-	-	-
歸屬於本公司業主之淨利	234,630	4.83%	187,279	4.59%	25.28%
基本每股盈餘(新台幣元)	0.33	-	0.27	-	22.22%
EBITDA	592,442	12.19%	473,685	11.62%	25.07%

# 重要資產負債表項目及財務指標(與上一季比較)

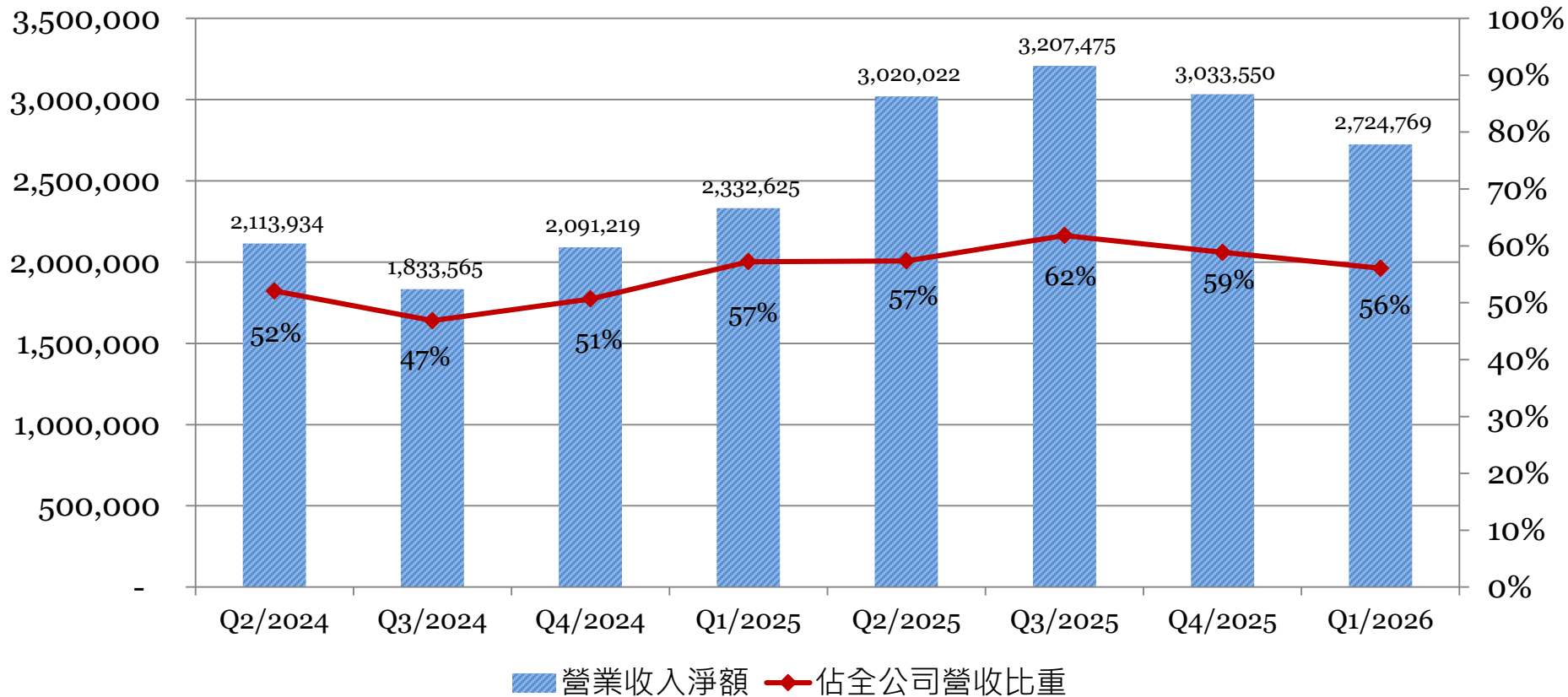
(單位：新台幣仟元)	Q1/2026	Q4/2025	季變化
現金及約當現金	3,066,961	2,718,816	12.81%
金融資產-非流動-及採用權益法之投資	2,346,166	1,833,683	27.95%
不動產、廠房及設備	8,432,023	7,807,304	8.00%
<b>資產總計</b>	<b>22,594,916</b>	<b>20,714,230</b>	<b>9.08%</b>
短期借款及應付短期票券	224,000	320,704	(30.15%)
一年或一營業週期內到期長期負債	184,002	456,432	(59.69%)
長期借款	228,203	1,498,454	(84.77%)
應付公司債	2,351,000	0	-
<b>負債總計</b>	<b>11,149,882</b>	<b>9,560,032</b>	<b>16.63%</b>
<b>權益總計</b>	<b>11,445,034</b>	<b>11,154,198</b>	<b>2.61%</b>
<b>當季EBITDA</b>	<b>592,442</b>	<b>762,747</b>	<b>(22.33%)</b>
<b>重要財務指標</b>			
負債比率	49.35%	46.15%	
應收帳款週轉天數(Q1)	87天	78天	
存貨週轉天數(Q1)	59天	44天	

# 重要資產負債表項目及財務指標(與去年同期比較)

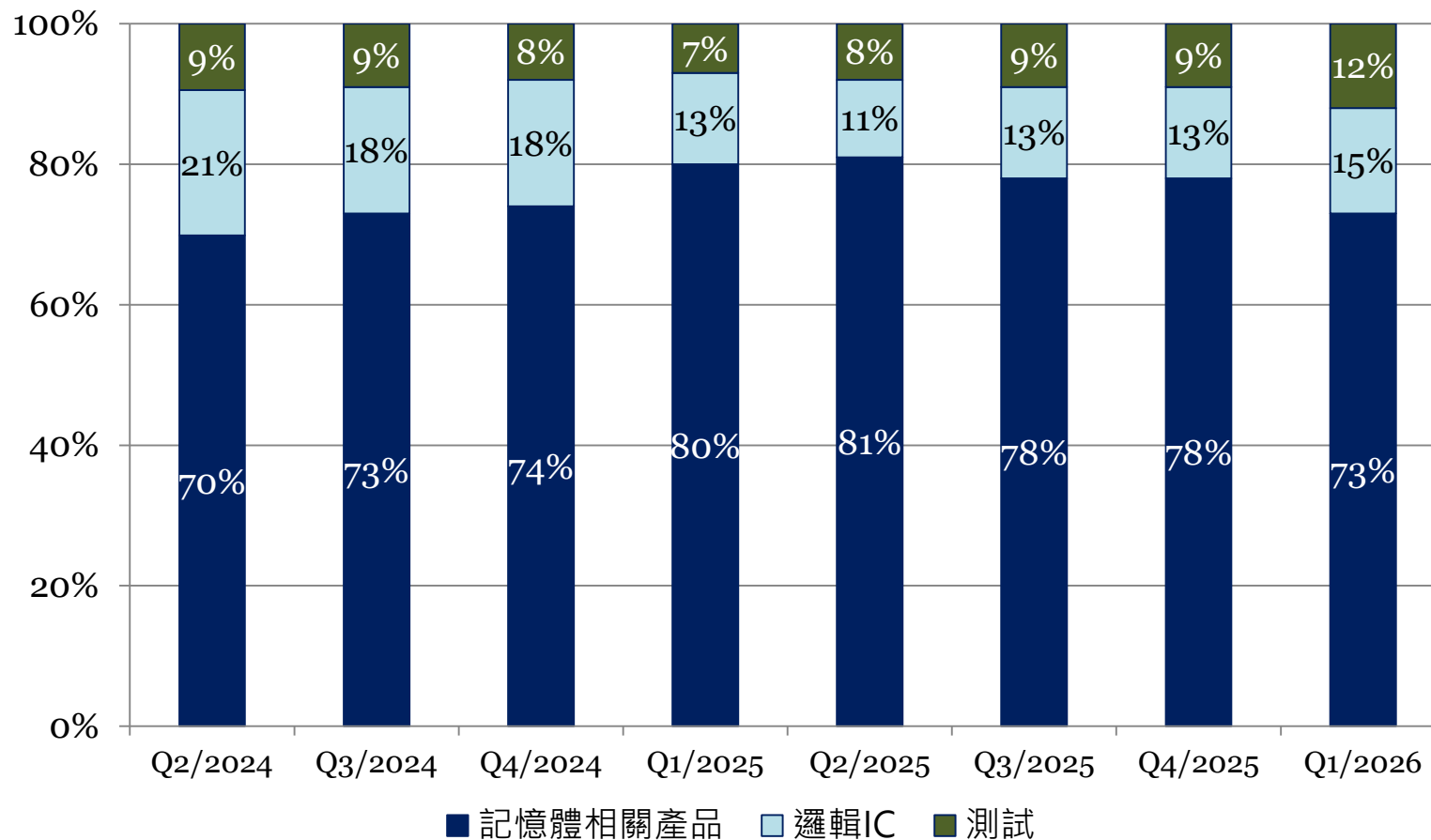
(單位：新台幣仟元)	Q1/2026	Q1/2025	年變化
現金及約當現金	3,066,961	3,963,243	(22.61%)
金融資產-非流動及採用權益法之投資	2,346,166	1,755,000	33.68%
不動產、廠房及設備	8,432,023	6,474,363	30.24%
<b>資產總計</b>	<b>22,594,916</b>	<b>19,015,286</b>	<b>18.83%</b>
短期借款及應付短期票券	224,000	-	100.00%
一年或一營業週期內到期長期負債	184,002	418,997	(56.09%)
長期借款	228,203	928,705	(75.43%)
應付公司債	2,351,000	0	-
<b>負債總計</b>	<b>11,149,882</b>	<b>7,937,407</b>	<b>40.47%</b>
<b>權益總計</b>	<b>11,445,034</b>	<b>11,077,879</b>	<b>3.31%</b>
<b>當季EBITDA</b>	<b>592,442</b>	<b>473,685</b>	<b>25.07%</b>
<b>重要財務指標</b>			
負債比率	49.35%	41.74%	
應收帳款週轉天數(Q1)	87天	90天	
存貨週轉天數(Q1)	59天	43天	

# IC封測業務

(單位：新台幣仟元)

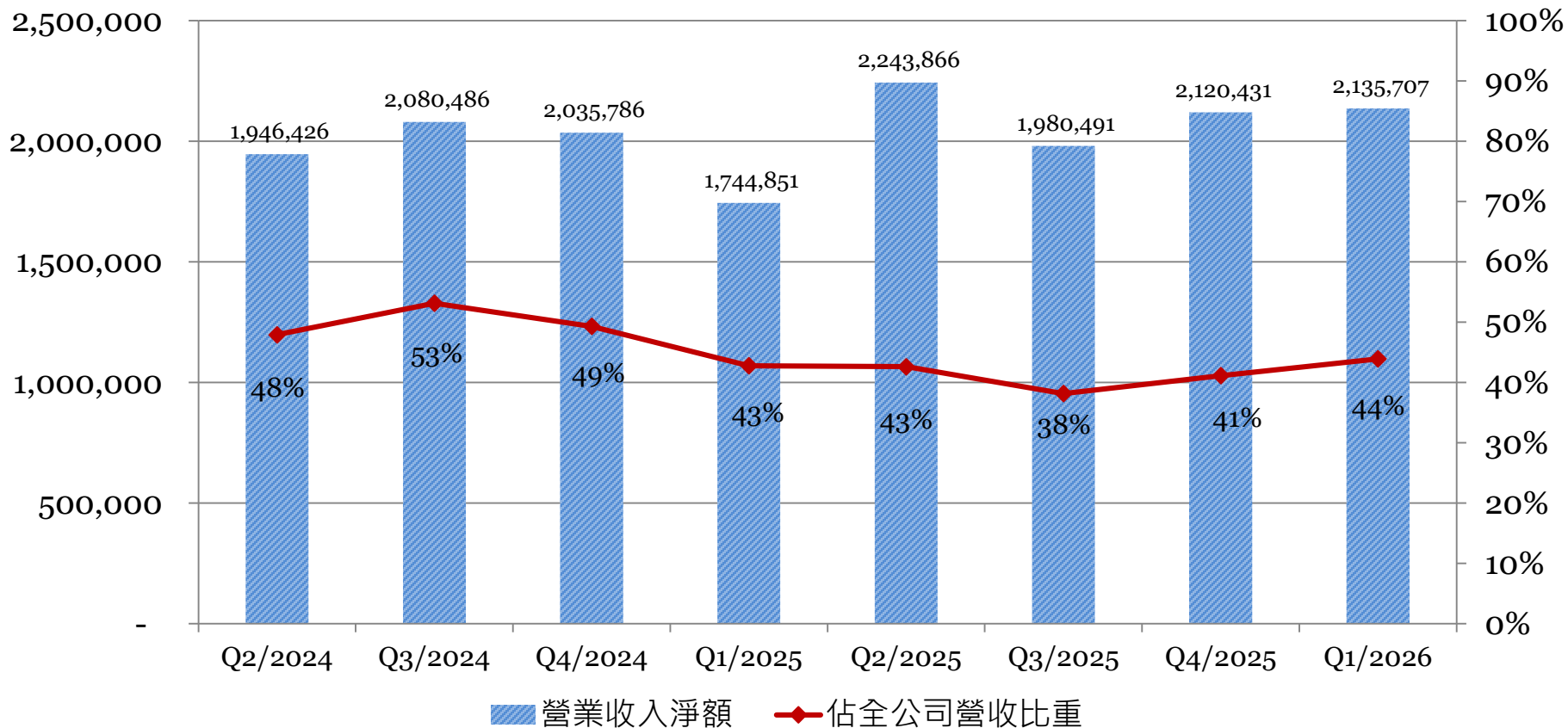


# 半導體封測營收-產品應用別佔比

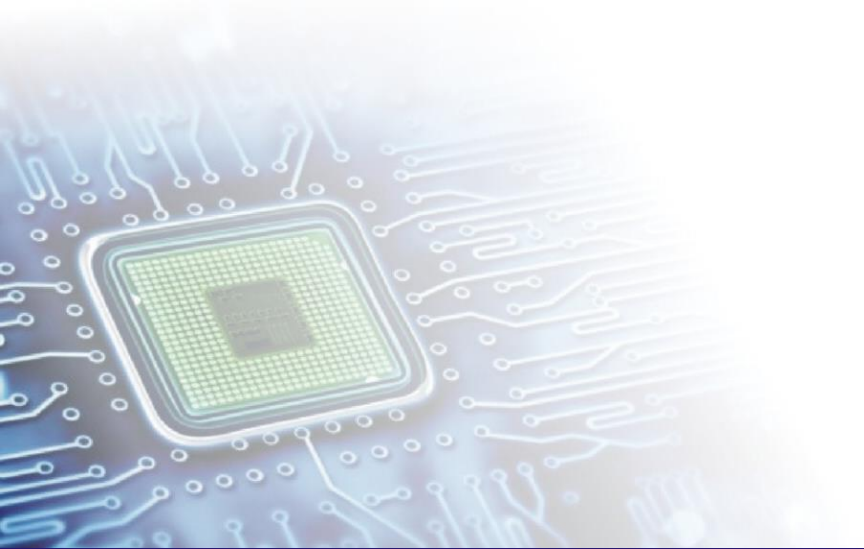


# EMS業務

(單位：新台幣仟元)



# 競爭優勢



“WHAT OSE  
COULD  
OFFER”

“QUALITY  
SPEED  
FLEXIBILITY”



- Capable of both IC & EMS / One-Stop Service.
- Professional experience with world-class customers. Strong Customer list.



- **Advanced Process Capability**
  - 25um wafer thickness
  - 16 Layers Die Stacking for micro SD/BGA/SD
  - Sip / Flip Chip / Wire Bond / Module Availability
  - High-end Technology

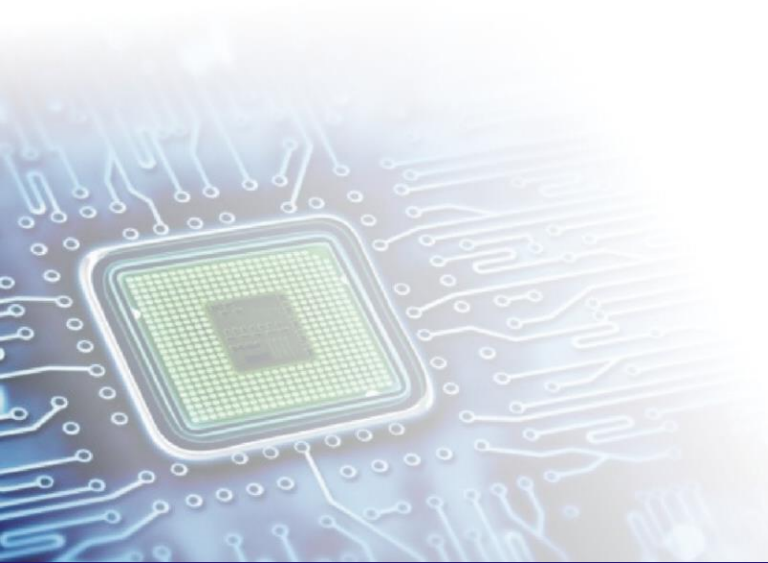


- Platform for Memory Manufacture
- MES Automation System



- Customer Oriented & Customization
- High Degree of Flexibility on capacity allocation

# Q&A



# 聲明

The presentation and the relevant information mentioned in this material have been compiled from both internal and external resources.

These forward looking statements involve known and unknown risks, uncertainties and other factors, including price variation, competition, global economy, exchange rate movement and market demand, which may cause actual results to differ materially from those implied by such forward-looking statements.

The forward looking statements expressed in this material reflect the Company's current view about the future as of today. The Company is not responsible for any updates if there are any changes in the future.